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NPN SILICON PHOTOTRANSISTOR LED LAMPS



Lead-Free Parts

LPT3363/S176-PF

DATA SHEET

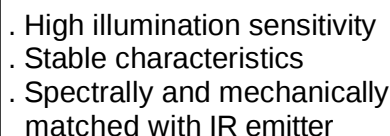
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Features



The LPT3363/S176-PF series are silicon nitride passivated NPN planar phototransistors with exceptionally stable characteristics and high illumination sensitivity. The cases of LPT3363/S176-PF are encapsulated in water clear plastic T1 3/4 package individually.

Note:1.All dimension are in millimeter tolerance is $\pm 0.25\text{mm}$ unless otherwise noted
2.Specifications are subject to change without notice

• MAXIMUM RATINGS(Ta=25°C)

PARAMETER	MAXIMUM RATINGS	UNIT
Power Dissipation	100	mw
Collector-Emitter Voltage	30	V
Emitter-Collector Voltage	5	V
Operating Temperature	-50°C TO +100°C	
Storage Temperature	-50°C TO +100°C	
Lead Soldering Temperature(1.6mm From Body)	260°C for 3 seconds	

• ELECTRICAL CHARACTERISTICS(Ta=25°C)

PARAMETER	SYMBOL	Min.	Typ.	Max.	UNIT	TEST CONDITION
Collector-Emitter Breakdown Voltage	$V_{(BR)CEO}$	30			V	$I_C=1mA$ $E_e=0mw/cm^2$
Emitter-Collector Breakdown Voltage	$V_{(BR)ECO}$	5			V	$I_E=100\mu A$ $E_e=0mw/cm^2$
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$			0.4	V	$I_C=0.5mA$ $E_e=20mw/cm^2$
Rise Time	T_r		5		μs	$V_{CE}=30V$ $I_C=800\mu A, R_L=1K\Omega$
Fall Time	T_f		5		μs	
Collector Dark Current	I_{CEO}			100	nA	$V_{CE}=10V$ $E_e=0mw/cm^2$
On State Collector Current	$I_{p(on)}$	1		2	mA	$V_{CE}=5v$ $E_e=1mw/cm^2$ $\lambda P=940nm$
		2		4	mA	
		4		8	mA	
		8			mA	

**Soldering Condition(Pb-Free)****1.Iron:**

Soldering Iron:30W Max

Temperature 350° C Max

Soldering Time:3 Seconds Max(One time only)

Distance:2mm Min(From solder joint to body)

2.Wave Soldering Profile

Dip Soldering

Preheat: 120° C Max

Preheat time: 60seconds Max

Ramp-up

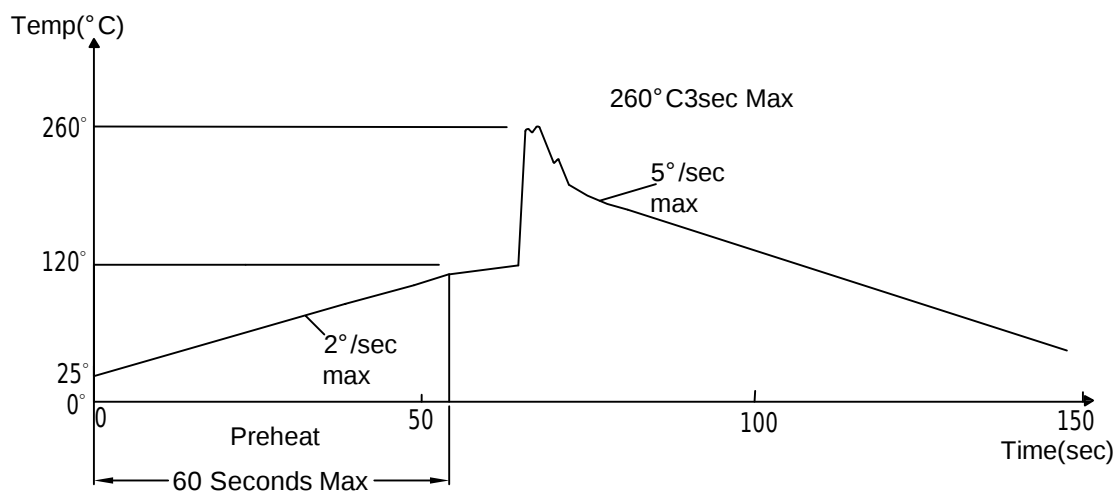
2° C/sec(max)

Ramp-Down:-5° C/sec(max)

Solder Bath:260° C Max

Dipping Time:3 seconds Max

Distance:2mm Min(From solder joint to body)



Note: 1.Wave solder should not be made more than one time.

2.You can just only select one of the soldering conditions as above.

**Reliability Test:**

Test Item	Test Condition	Description	Reference Standard
Operating Life Test	1.Under Room Temperature 2.If=20mA 3.t=1000 hrs (-24hrs, +72hrs)	This test is conducted for the purpose of determining the resistance of a part in electrical and thermal stressed.	MIL-STD-750: 1026 MIL-STD-883: 1005 JIS C 7021: B-1
High Temperature Storage Test	1.Ta=85 °C±5°C 2.t=1000 hrs (-24hrs, +72hrs)	The purpose of this is the resistance of the device which is laid under condition of high temperature for hours.	MIL-STD-883:1008 JIS C 7021: B-10
Low Temperature Storage Test	1.Ta=-40 °C±5°C 2.t=1000 hrs (-24hrs, +72hrs)	The purpose of this is the resistance of the device which is laid under condition of low temperature for hours.	JIS C 7021: B-12
High Temperature High Humidity Test	1.Ta=65 °C±5°C 2.RH=90%~95% 3.t=240hrs ±2hrs	The purpose of this test is the resistance of the device under tropical for hours.	MIL-STD-202:103B JIS C 7021: B-11
Thermal Shock Test	1.Ta=105 °C±5°C & -40°C±5°C (10min) (10min) 2.total 10 cycles	The purpose of this is the resistance of the device to sudden extreme changes in high and low temperature.	MIL-STD-202: 107D MIL-STD-750: 1051 MIL-STD-883: 1011
Solder Resistance Test	1.T.Sol=260 °C±5°C 2.Dwell time= 10 ±1sec.	This test intended to determine the thermal characteristic resistance of the device to sudden exposures at extreme changes in temperature when soldering the lead wire.	MIL-STD-202: 210A MIL-STD-750: 2031 JIS C 7021: A-1
Solderability Test	1.T.Sol=230 °C±5°C 2.Dwell time=5 ±1sec	This test intended to see soldering well performed or not.	MIL-STD-202: 208D MIL-STD-750: 2026 MIL-STD-883: 2003 JIS C 7021: A-2